



# **Additional Information**



Resources





Accessories

Samples

# **Agency Approvals**

Agency	Agency File Number
<i>7U</i> :	E230531

## **Maximum Ratings and Thermal Characteristics**

(T<sub>A</sub>=25 °C unless otherwise noted)

Parameter	Symbol	Value	Unit	
Peak Pulse Power Dissipation at	8/20µs (Note 2)	D	1200	W
$T_A = 25^{\circ}C$ (Note 1)	10/1000µs (Note 3)	P <sub>PPM</sub>	200	W
Thermal Resistance	$R_{\theta JA}$	220	°C/W	
Thermal Resistance	R <sub>eJL</sub>	100	°C/W	
Operating Tempera	$T_{J}$	-55 to 150	°C	
Storage Temperatur	T <sub>STG</sub>	-55 to 150	°C	

## Notes:

1. Non-repetitive current pulse, per Fig. 4 and derated above  $T_J$  (initial) =25°C per Fig. 3.

# **Description**

SMF3.3 is designed specifically to protect sensitive electronic equipment from voltage transients induced by lightning and other transient voltage events.

### **Features and Benefits**

- 200W peak pulse power capability at 10/1000µs waveform, repetition rate (duty cycle): 0.01%
- 1200W peak pulse power capability at 8/20us waveform
- Excellent clamping capability
- Compatible with industrial standard package SOD-123FL
- Low profile: maximum height of 1.08mm.
- For surface mounted applications to optimize board space
- Typical failure mode is short from over-specified voltage or current
- Whisker test is conducted based on JEDEC JESD201A per its table 4a and 4c
- IEC 61000-4-2 ESD 30kV(Air), 30kV (Contact)
- ESD protection of data lines in accordance with IEC 61000-4-2

- EFT protection of data lines in accordance with IEC 61000-4-4
- Fast response time: typically less than 1.0ns from 0 Volts to VBR min
- High temperature soldering: 260°C/30 seconds at terminals
- Built-in strain relief
- Meet MSL level1, per J-STD-020C, LF maximun peak of 260°C
- Matte tin lead–free plated
- Halogen-free and RoHScompliant
- Pb-free E3 means 2nd level interconnect is Pb-free and the terminal finish material is tin(Sn) (IPC/JEDEC J-STD-609A.01)

# **Applications**

SMF3.3 series is ideal for the protection of portable electronics/ hard drives, notebooks, VCC busses, POS terminal, SSDs, power supplies, monitors, and vulnerable circuit used in other consumer applications.

# **Functional Diagram**



## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

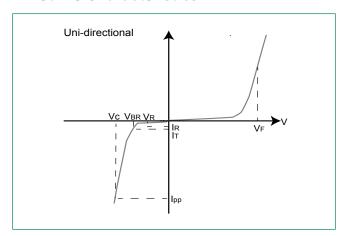
Part Number		Volta	Breakdown Voltage V <sub>BR</sub> (Volts) @ I <sub>T</sub>		Reverse Stand off Voltage V <sub>R</sub>	Maximum Reverse Leakage @ V <sub>R</sub>	Maximum Peak Pulse Current (10/1000µS)	Maximum Clamping Voltage @l <sub>pp</sub> (10/1000µS)	Maximum Peak Pulse Current (8/20µS)	Maximum Clamping Voltage @I <sub>pp</sub> (8/20uS)
		MIN	MAX	(mA)	(V)	I <sub>R</sub> (μA)	I <sub>pp</sub> (A)	V <sub>c</sub> (V)	I <sub>pp</sub> (A)	V <sub>c</sub> (V)
SMF3.3	33	3.4	4.3	10	3.3	0.5	30.0	6.8	120.0	10.0

#### Notes

- 1.  $V_{BR}$  measured after  $I_{T}$  applied for 300 $\mu$ s,  $I_{T}$  = sequare wave pulse or equivalent.
- 2. Surge current waveform per 10/1000µs exponential wave and derated per Fig.2.
- 3. All terms and symbols are consistent with ANSI/IEEE C62.35.
- 4. Surge current waveform per 8/20µs exponential wave and derated per Fig.6



# **I-V Curve Characteristics**



- P<sub>PPM</sub> Peak Pulse Power Dissipation Max power dissipation
- V<sub>a</sub> Stand-off Voltage -- Maximum voltage that can be applied to the TVS without operation
- ${f V}_{_{BR}}$  **Breakdown Voltage** Maximum voltage that flows though the TVS at a specified test current (IT)
- I<sub>s</sub> Reverse Leakage Current Current measured at VR
- V, Forward Voltage Drop for Uni-directional

Note: VF distribution range from 7V to 16V at IF 1mA.

# Ratings and Characteristic Curves (T<sub>A</sub>=25°C unless otherwise noted)

**Figure 1 -**TVS Transients Clamping Waveform

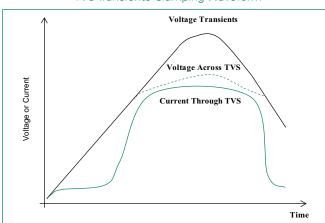


Figure 2 -Peak Pulse Power Rating Curve

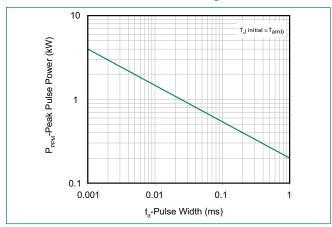
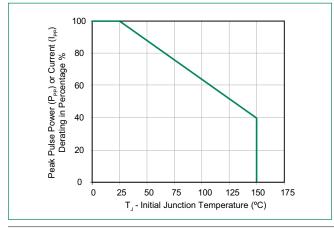
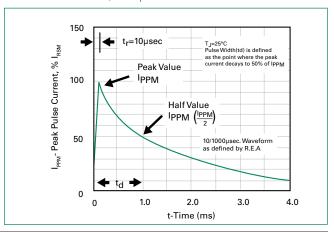


Figure 3 -Peak Pulse Power Derating Curve



**Figure 4** - 10/1000µS Pulse Waveform





25.0

30.0

Figure 5 -Capacitance vs. Reverse Bias

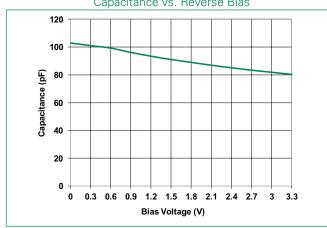


Figure 6 8/20µS Pulse Waveform

110%
100%
90%
80%
80%
40%
30%
20%

10%

0.0

5.0

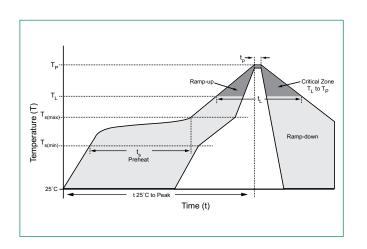
10.0

15.0

Time (µs)

# **Soldering Parameters**

Reflow Cond	lition	Lead-free assembly	
	-Temperature Min (T <sub>s(min)</sub> )	150°C	
Pre Heat	-Temperature Max (T <sub>s(max)</sub> )	200°C	
	-Time (min to max) (t <sub>s</sub> )	60 - 120 secs	
Average ram peak	p up rate (Liquidus Temp (T <sub>L</sub> ) to	3°C/second max	
T <sub>S(max)</sub> to T <sub>L</sub> -	Ramp-up Rate	3°C/second max	
Reflow	-Temperature (T <sub>L</sub> ) (Liquidus)	217°C	
	-Time (min to max) (t <sub>L</sub> )	60 - 150 seconds	
Peak Temper	ature (T <sub>P</sub> )	260 <sup>+0/-5</sup> °C	
Time within	5°C of actual peak Temperature (t <sub>p</sub> )	30 seconds max	
Ramp-down	Rate	6°C/second max	
Time 25°C to	peak Temperature (T <sub>p</sub> )	8 minutes max.	
Do not excee	ed	260°C	



# **Physical Specifications**

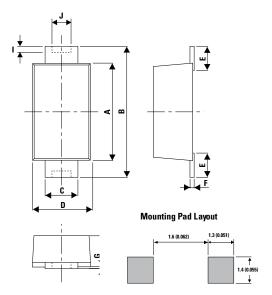
Case	SOD-123FL plastic over passivated junction
Polarity	Color band denotes cathode except bipolar
Terminal	Matte tin-plated leads, solderable per JESD22-B102

# **Environmental Specification**

High Temp. Storage	JESD22-A103
HTRB	JESD22-A108
Temperature Cycling	JESD22-A104
MSL	JEDEC-J-STD-020, LEVEL 1
H3TRB	JESD22-A101
RSH	JESD22-A111



# **Dimensions - SOD-123FL Package**

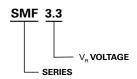


Dimensions	Millin	neters	Inches		
Dimensions	Min	Max	Min	Max	
А	2.70	3.10	0.106	0.122	
В	3.50	3.90	0.138	0.154	
С	0.85	1.05	0.033	0.041	
D	1.70	2.00	0.067	0.079	
E	0.43	0.83	0.017	0.033	
F	0.10	0.25	0.004	0.010	
G	0.00	0.10	0.000	0.004	
Н	0.90	1.08	0.035	0.043	
1	0.00	0.20	0.000	0.008	
J	0.40	0.60	0.016	0.024	

**Part Marking System** 

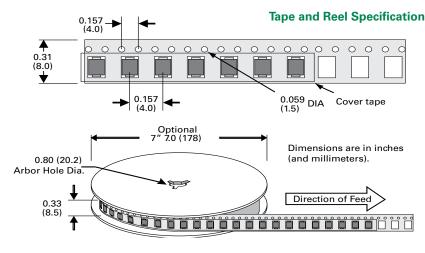
Cathode Band

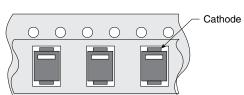
# Part Numbering System



# Packaging Options Marking Code Trace Code Marking Y:Year Code M: Month Code X: Plant Code

Part number	Component Package	Quantity	Packaging Option	Packaging Specification
SMF3.3	SOD-123FL	3000	Tape & Reel – 8mm tape/7" reel	EIA RS-481





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